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VERSION WITH MARKINGS TO SHOW CHANGES MADE
IN THE CLAIMS

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1. (Once amended) A method for manufacturing a semiconductor package, said method comprising:

providing a wafer including one or more semiconductor chips, each chip having one or more mirrors formed thereon[,] and a plurality of bond pads formed on a periphery of the chip;

forming a photoresist over the one or more mirrors;

singulating the one or more semiconductor chips from the wafer;

mounting the one ore more semiconductor chip on a top surface of a base substrate;

electrically interconnecting the bond pads of the semiconductor chip to the base substrate; and

removing the photoresist from the semiconductor chips.

5. (Once amended) A method for manufacturing digital micro-mirror device (DMD) packages, said method comprising:

providing a wafer including a plurality of DMD semiconductor chips, each chip having one or more mirrors formed on substantially the center of an active surface of the chip, a plurality of electrode pads formed on the periphery of the active surface;

forming a photoresist over the mirrors;

forming a metallic layer on a back surface of the wafer;

separating the wafer into the individual semiconductor chips;

mounting each semiconductor chip on an upper surface of a base substrate using a metallic adhesive;

interconnecting the electrode pads of the semiconductor chip to the base substrate with one or more bonding wires;

removing the photoresist from the semiconductor chips;

forming an anti-sticking film on the active surface of the semiconductor chip for protecting the semiconductor chips from dust and moisture; and

hermetically sealing the semiconductor chip and the bonding wires on the upper surface of the base substrate.

9. (Once amended) The method of claim 5, wherein said [metal] metallic adhesive is solder.

Claims 16-18 are new.